ABSTRACT

METHOD AND APPARATUS FOR STACKED DIE PACKAGING

A method and apparatus for stacked die packaging provide a leadframe configured for supporting a lower semiconductor die. At least one pillar is formed on the leadframe for supporting an upper semiconductor die. The pillar is formed integrally with and of the same material as the leadframe, and is sized to have a predetermined height that is higher than the height of such a lower semiconductor die plus the height of bonding wires for such a lower semiconductor die plus a predetermined spacing between such bonding wires and the bottom of an upper semiconductor die to be supported on the at least one pillar. (FIG. 25)